

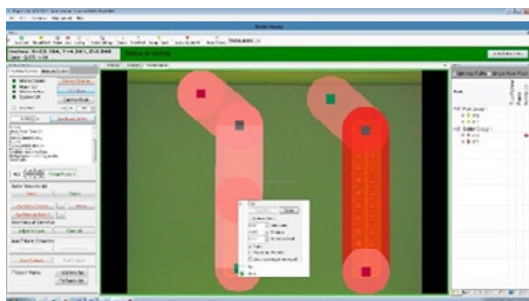
Novo® Series: Model 103

Selective Soldering with combined Flexibility and Modularity



The Novo® 103 is a robust selective soldering platform delivering an exceptional combination of versatility, productivity and value. The Novo® 103 has many unique features, including high speed Z-axis motion for faster processing time and reduced soldering cycle.

Flexibility. With its feature rich, graphics-based programming and machine control software, the Novo® 103 is specially designed for demanding selective soldering applications. Set-up and time to first article is significantly reduced to within 10-15 minutes. The SWAK-OS 4.0 software features seamless fiducial recognition, live teach cameras, real time data collection, SQL backend data extraction and complete FIS capability for shop floor integration.



SWAK-OS 4.0 graphics-based programming software

Features and Benefits

- Selective soldering of printed circuit boards as large as 610 x 457 mm (24.0 x 18.0 in.)
- Standalone platform ideal for prototype, cell manufacturing or batch production requirements
- Interchangeable solder pots and pumps compatible with tin-lead, lead-free and HMP solder alloys
- Choice of single selective solder nozzle, dual selective nozzles with independent control or 75 mm wide wave soldering nozzle
- SWAK-OS 4.0 graphics-based programming and machine control software enables fast and straightforward program creation

Soldering Technology. With its flexible configuration, the Novo® 103 is a versatile selective soldering platform capable of processing tin-lead, lead-free or HMP solder alloys. Interchangeable solder pots and pumps are available with either single selective solder nozzle, dual selective nozzles with independent control or 75 mm (3.0 in.) wide wave soldering nozzle. The nitrogen inerted dual nozzle system enables the use of multiple size nozzles within the same program further enhancing flexibility and productivity.

Process Control. Nordson SELECT's optional closed-loop rotary encoders and other advanced process control capabilities have been incorporated into the Novo® 103, enhancing solder quality, precision and yield capabilities.

Value. With a reputation for innovation, comprehensive process solutions from Nordson SELECT ensure a maximum return on investment and low cost of ownership. From initial process development through full-scale production, you are supported by our experienced worldwide engineering, applications development and technical service network.

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Novo® 103 Features

The Novo® 103 is a fully configured selective soldering platform and is a reliable and cost-effective solution for many demanding through-hole and SMT mixed-technology soldering applications including:

- **Printed circuit board assemblies and other solderable substrates**
- **Interchangeable tin-lead and lead-free soldering**

Choice of soldering nozzles - single selective nozzle, dual selective nozzles or 75 mm wave nozzle



Single solder nozzle

Dual solder nozzles

75 mm wave nozzle

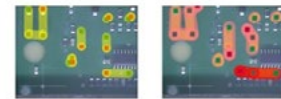


Standard atomizing spray flux applicator and available FluxJet precision drop-jet dispenser

Interchangeable solder pots and pumps for tin-lead, lead-free and HMP solder alloys

Single monitor and available dual monitors for simultaneous viewing of all process functions

SWAK-OS 4.0 graphics-based programming and machine control software



Seamlessly creates true-to-scale image of entire board

Paint flux and solder paths to create and edit programs

Standalone platform with universal PCB location rails and motor driven adjustment

Standard Features

Universal PCB location rails with motor driven adjustment and multiple board stops for processing several boards at one time
High speed Z-axis motion
Closed-loop rotary encoders
Atomizing spray flux applicator
Tin-lead solder pot and pump assembly with 6 mm and 12 mm quick change magnetically coupled ControlFlow nozzles
Automatic wave height monitoring and adjust system
Solder alloy verification system
Heated nitrogen inerting system
Fiducial alignment and programming camera
Process viewing camera
SWAK-OS 4.0 graphics-based programming and machine control software

- Fully-automated fiducial alignment and board mapping
- Board warp compensation
- On-board help videos
- Remote machine diagnostics
- Complete FIS capability

Offline programming software
Single monitor

Optional Features

Universal PCB location fixture
FluxJet precision drop-jet dispenser
In-process flux verification system for drop-jet
Dual flux heads, 2 atomizing spray heads, 2 drop-jet flux dispensers or one of each
Topside infrared preheater with closed-loop control
Dual process viewing cameras
Automatic solder nozzle tinning system
Automatic solder pot level monitoring and fill system
Lead-free solder pot and pump assembly (titanium)
HMP solder pot and pump assembly
Dual nozzle solder pot and pump assembly, tin-lead or lead-free (titanium)
3-25 mm ControlFlow nozzles or 4-25 mm mini-wave nozzles
75 mm (3.0 in.) wide wave nozzle and pump assembly, tin-lead or lead-free (titanium)
2.27 kg (5.0 lbs.) solder feeder
Solder pot exchange cart with warming controls
Nitrogen de-bridging knife
Dual monitors
Six channel thermal data logging system
Barcode reader

Specifications

Motion System

Z accuracy ⁽¹⁾ :	±50 µm (0.002 in.)
Z repeatability ⁽²⁾ :	±50 µm (0.002 in.), 3 sigma
Z velocity:	0.15 m/s peak (6 in./s)
X-Y accuracy ⁽¹⁾ :	±50 µm (0.002 in.)
X-Y repeatability ⁽²⁾ :	±50 µm (0.002 in.), 3 sigma
X-Y velocity:	0.2 m/s peak (8 in./s)

Computer

PC with Windows® operating system

Software

SWAK-OS 4.0 graphics-based programming and machine control software

Solder Pot Capacity and Weight

Capacity ⁽³⁾ :	Approx. 13.6 kg (30.0 lbs.)
Total weight of tin-lead solder together with solder pot and pump assembly ⁽³⁾ :	Approx. 24.0 kg (53.0 lbs.)
Total weight of lead-free solder together with solder pot and pump assembly ⁽³⁾ :	Approx. 21.3 kg (47.0 lbs.)
Max. tin-lead/lead-free temperature:	350°C
Max. HMP temperature:	400°C

Solderable Area (X-Y)

Single ControlFlow, dual ControlFlow or mini-wave nozzles ^(4, 5, 6):
Max. 610 x 457 mm (24.0 x 18.0 in.)
Min. 50 x 50 mm (2.0 x 2.0 in.)

Preheating

Scalable infrared preheating from 1.0 kW to 6.0 kW

Board Handling Capability

Max. board size:	610 x 457 mm (24.0 x 18.0 in.)
Min. board size:	50 x 50 mm (2.0 x 2.0 in.)

Board Clearance

Max. overboard clearance:	102 mm (4.0 in.)
Max. underboard clearance:	102 mm (4.0 in.)

Facilities Requirements

System footprint:	1400 x 1421 mm (55.1 x 55.9 in.)
Compressed Air:	6 bar (90 psi.) min., 7 bar (100 psi) max.
Power (mains) ⁽⁷⁾ :	Power supply accommodates 208/220-240VAC, 60 Hz single phase, 50 A
Nitrogen ⁽⁸⁾ :	99.999% (5.0) pure, 4-7 bar (60-100 psi) 1.2 m3/hour consumption
Ventilation:	595 m3/hour (350 SCFM), two 100 mm (4.0 in.) dia. ducts
System weight ^(9, 10) :	422 kg (930 lbs.)

- (1) Accuracy as measured at extremes of travel.
- (2) Repeatability is measured at full rated system speed.
- (3) Solder capacity and total weight of solder pot and pump assembly varies depending on solder alloy.
- (4) Substrates as small as 50 x 50 mm (2.0 x 2.0 in.) are possible without the need for fixturing or other tooling.
- (5) Contact factory regarding smaller boards/carriers.
- (6) 2.27 kg (5.0 lbs.) solder feeder is not compatible with dual nozzle solder pot and pump assembly.
- (7) Electrical power varies depending on configuration.
- (8) Nitrogen consumption is solder nozzle dependent and machine configuration dependent.
- (9) System weight varies depending on configuration.
- (10) Configuration dependent. Other configurations may be available. Contact Nordson SELECT.

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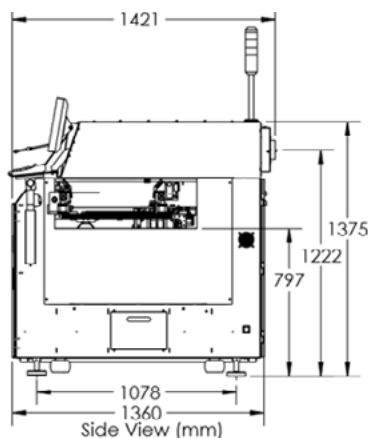
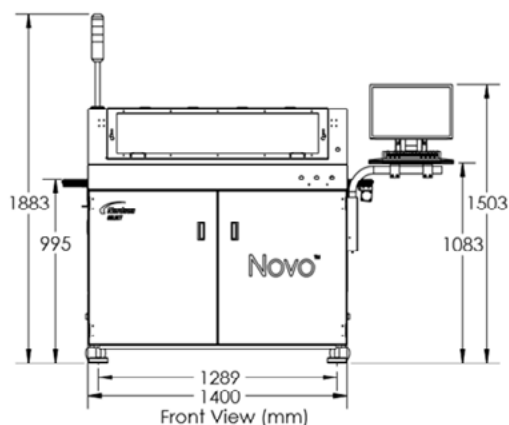
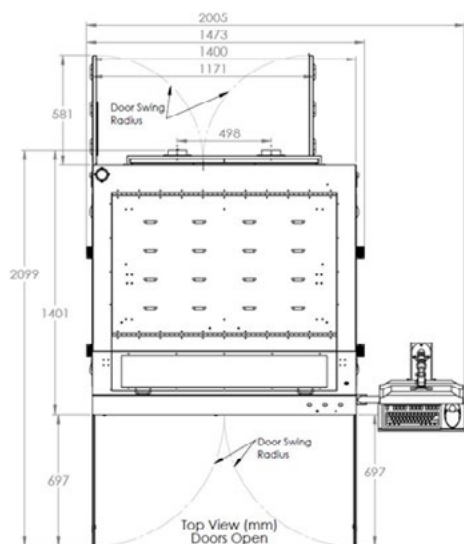
Standards Compliance

SMEMA

Additional options may be available: contact Nordson SELECT for further information.

Novo[®] Series: Model 103

Dimensions are in Millimeters



For more information
speak with your local sales
rep or contact your regional
office.

nordsonselect.com

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